



Material Content Data Sheet



Sales Product Name		IPU60R2K1CE		Issued		27. September 2017		
MA#		MA001505602						
Package		PG-TO251-3-345		Weight*		384.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.272	0.33	0.33	3304	3304
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		542	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		163	
	non noble metal	copper	7440-50-8	208.238	54.10	54.17	541015	541720
wire	non noble metal	aluminium	7429-90-5	4.506	1.17	1.17	11707	11707
encapsulation	organic material	carbon black	1333-86-4	0.685	0.18		1780	
	plastics	epoxy resin	-	18.498	4.81		48059	
	inorganic material	silicondioxide	60676-86-0	117.840	30.62	35.61	306156	355995
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18328	18328
solder	noble metal	silver	7440-22-4	0.041	0.01		106	
	non noble metal	tin	7440-31-5	0.033	0.01		84	
	non noble metal	lead	7439-92-1	1.553	0.40	0.42	4035	4225
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.46	6.47	64637	64721
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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